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INFORMATION DISCLOSURE CITATION FORM FOR PATENT APPLICATION (FORM PTO-1449) (Substitute)		Docket No.: Y0R920030196US1	Serial No.: 10/700,327			
		Applicant(s): Paul S. ANDRY et al.				
		Filing Date: 11/03/03	Group:			
U.S. PATENTS						
Initials	Patent Number	Issue Date	Name	Class	Sub-class	Filing date
/MW/	5,244,143	09/14/93	Ference et al.	X	X	
/MW/	5,775,569	07/07/98	Berger et al.			
/MW/	5,998,292	12/07/99	Black et al.	X	X	
/MW/	6,506,332	01/14/03	Pedigo			
/MW/	6,593,644	07/15/03	Chiu et al.			
FOREIGN PATENT DOCUMENTS						
Initials	Document Number	Date	Country	Name		Translation? Yes/No/n/a
OTHER DOCUMENTS (Title, Author, Date, Pages, Etc., if known)						
/MW/	"Filling the via hole of IC by VPES (Vacuum Printing Encapsulation Systems for stacked chip (3D Packaging), A. Okuno et al., 2002 Electronics Components and Technology Conference					
Examiner's Signature: /Mary Wilczewski/			Date Considered: 07/07/2007			
Initial if reference was considered, whether or not citation is in conformance with MPEP. Mark through citation if not considered. Include a copy of this citation form with your next correspondence to the Applicant(s).						